

LISTING OF THE CLAIMS

Claims 1-62: (canceled).

63 (currently amended): A semiconductor device, using a bonding material for linking a semiconductor terminal to a connecting terminal for an outside circuit, characterized by reinforcing the bonding material and/or a joint between the semiconductor terminal and the connecting terminal with a reinforcing material comprising a metal coating covering the bonding material and/or joint and a diffusion layer at an interface between the metal coating and the bonding material and/or joint, wherein the metal coating is a metal consisting essentially of one or more of nickel, cobalt, chromium, platinum, palladium and tungsten.

64 (currently amended): A semiconductor device, using a bonding wire for linking a semiconductor terminal to a connecting terminal for an outside circuit, characterized by reinforcing the bonding wire, either partially or wholly, with a reinforcing material comprising a metal coating covering the bonding wire, a diffusion layer at an interface between the metal coating and the bonding wire, after bonding work, wherein the metal coating is a metal consisting essentially of one or more of nickel, cobalt, chromium, platinum, palladium and tungsten.

65 (canceled).

66 (canceled).

67 (previously presented): A semiconductor device according to claim 64 characterized in that the bonding wire is fabricated from any one of gold, copper, aluminum, silver and an alloy of any of these metals.

68 (previously presented): A semiconductor device according to claim 67, wherein the bonding wire is gold or gold alloy and an outermost surface of the bonding wire has a gold concentration of 99% or less.

69 (previously presented): A semiconductor according to claim 64, characterized by coating semiconductor terminal, the connecting terminal and the bonding wire with resin.

70 (previously presented): A semiconductor device according to claim 63 or 64, characterized by forming the connecting terminal using a substrate, a lead frame or a TAB tape.

71 (previously presented): A semiconductor device according to claim 63, characterized by forming the semiconductor terminal on any one of a semiconductor chip, a substrate, a lead frame or a TAB tape.